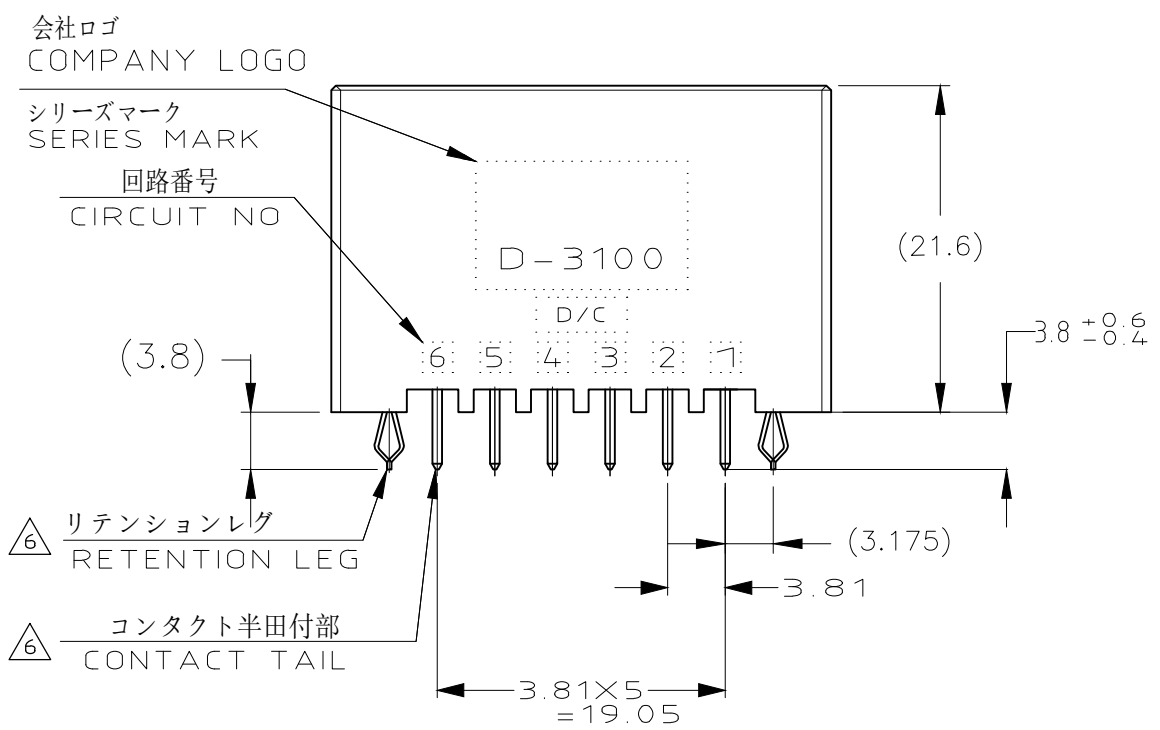
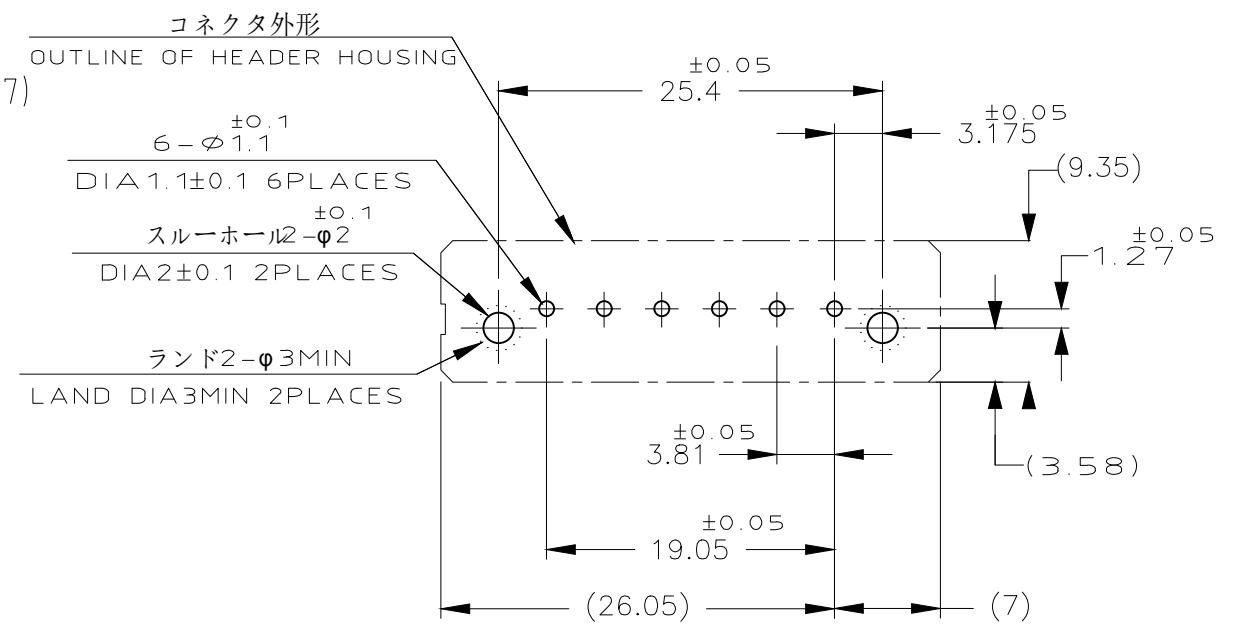
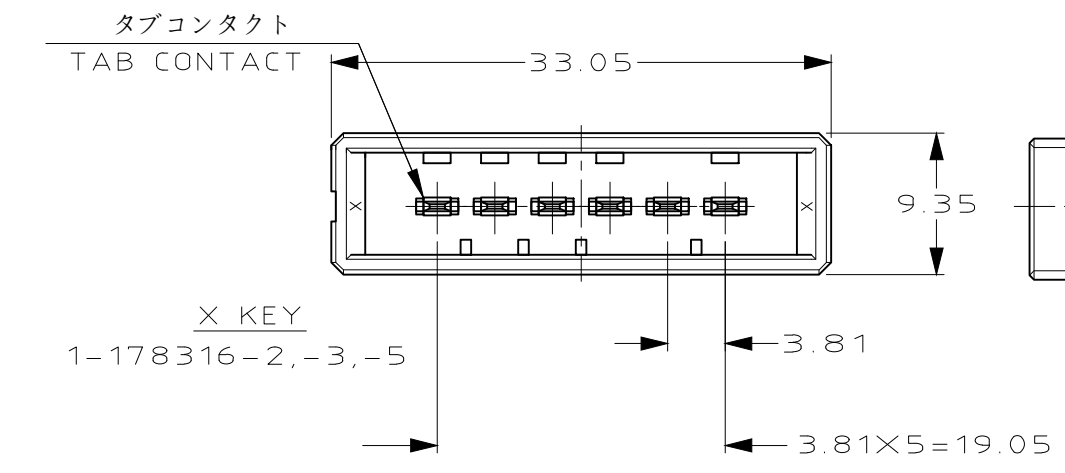


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REVISIONS					
P	LTR	DESCRIPTION	DATE	DWN	APVD
	C2	REVISED PER ECR-18-010496	04JUN2018	K.T	E.I

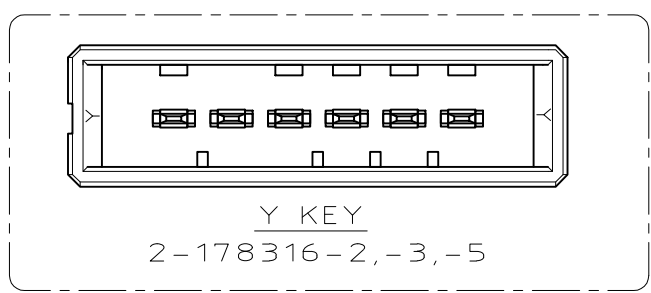


推奨基板取付け穴寸法
 PC 基板厚: 1.6±0.1
 (非累積公差)
 (コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
 PC BOARD THICKNESS: 1.6±0.1
 (NOT ACCUMULATE TOLERANCE)
 (CONNECTOR MOUNT SIDE)

1. MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER
 CONTACT: COPPER ALLOY
 RETENTION LEG: COPPER ALLOY
2. FINISH (CONTACT AREA): 0.38μm MIN GOLD PLATING OVER Ni PLATING
3. FINISH (CONTACT AREA): 0.76μm MIN GOLD PLATING OVER Ni PLATING
4. FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
5. FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL
7. GENERAL TOLERANCE
- | | |
|------------|-------|
| ≤ 10 | ±0.3 |
| 10 < ≤ 30 | ±0.4 |
| 30 < ≤ 100 | ±0.45 |
| ANGLE | ±3° |

1. 材料 ハウジングガラス入り熱可塑性
 ポリエステル樹脂
 コンタクト銅合金
 リテンションレグ銅合金
2. めっき コンタクト全面Ni下地
 接触部 0.38μm MIN 金めっき
3. めっき コンタクト全面Ni下地
 接触部 0.76μm MIN 金めっき
4. めっき コンタクト全面Ni下地
 接触部 2.0 μm MIN スズめっき
5. めっき リテンションレグとコンタクト半田付部
 ニッケル下地の上にスズめっき
7. 一般公差
- | | |
|------------|-------|
| 10以下 | ±0.3 |
| 10を超え30以下 | ±0.4 |
| 30を超え100以下 | ±0.45 |
| 角度 | ±3° |



6	4	1,2-178316-5
6	3	1,2-178316-3
6	2	1,2-178316-2
(FINISH)		製品番号 (PART NO.)

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN K.IKEDA 22DEC1994	TE Connectivity Ltd.			
DIMENSIONS: mm		CHK S.MANABE 10JAN1995				
TOLERANCES UNLESS OTHERWISE SPECIFIED.		APVD S.MANABE 10JAN1995	NAME			
0 PLC ±-		PRODUCT SPEC	6POS SINGLE ROW			
1 PLC ±-		108-5349	VERTICAL HDR ASSY			
2 PLC ±-		APPLICATION SPEC	DYNAMIC 3100			
3 PLC ±-		114-5148	SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
4 PLC ±-		WEIGHT	A3	-	C=178316	-
ANGLES ±-		MATERIAL SEE NOTE	CUSTOMER DRAWING		SCALE 2:1	SHEET 1 OF 1
FINISH SEE NOTE		SCALE 2:1		SHEET 1 OF 1		REV C2

Mouser Electronics

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